AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-7. (cancelled)

- 8. (currently amended) A mold for making a <u>heat curable</u> composite material part, comprising:
- a liquid coating of a stripping composition on the mold, wherein,

the stripping composition is [[a]] solvent-free $\underline{\text{and is}}$ polymerized by heating, and

the stripping composition comprises:

- 100 parts by weight of a base ingredient constituted by an epoxy polydimethylsiloxane;
- \cdot 0.5 to 10 parts by weight of a polymerization agent for polymerizing the base ingredient and constituted by a diaryliodonium salt;
- \cdot 5 to 10 parts by weight of an anti-adhesion modulator constituted by a silicone polymer an epoxy polydimethylsiloxane which is not polymerized and
- an anti-stick agent making the composition less tacky prior to polymerization, which comprises at least one vinyl ether compound, and said at least one vinyl ether compound is present at a concentration of 8 to 12 parts by weight dodecyl monovinyl

ether in the stripping composition and 8 to 12 parts by weight of cyclohexane dimethanol divinyl ether in the stripping composition.

9-12. (cancelled)

13. (currently amended) The mold according to claim 8, wherein

the polymerization agent is 5 to 7 parts by weight; and

said anti-adhesion modulator is an epoxy
polydimethylsiloxane; and

the anti-stick agent comprises two vinyl ether compounds, which are each present at a concentration in the range 8 to 12 parts by weight in said stripping composition, and

said two vinyl ether compounds are a dodecyl monovinyl ether and a cyclohexane dimethanol divinyl ether.

- 14. (previously presented) The mold according to claim 13, wherein
 - · the polymerization agent is 6 parts by weight;
 - \cdot the anti-adhesion modulate is 8 parts by weight; and
- \cdot the dodecyl monovinyl ether is present at a concentration of 11.4 parts by weight, and

- \cdot the cyclohexane dimethanol divinyl ether is present at a concentration of 11.4 parts by weight.
- 15. (currently amended) A wipe or cloth impregnated in [[a]] the stripping composition presenting the characteristics of claim 8.
- 16. (currently amended) A method of molding a <u>heat</u> <u>curable</u> composite material part, comprising:

forming a composite material in a mold coated by a liquid stripping composition, wherein,

the surface of the mold is coated with the stripping composition to a thickness of about one micrometer,

the stripping composition is [[a]] solvent-free \underline{and} is polymerized by heating, and

the stripping composition comprises:

- 100 parts by weight of a base ingredient constituted by an epoxy polydimethylsiloxane;
- \cdot 0.5 to 10 parts by weight of a polymerization agent for polymerizing the base ingredient and constituted by a diaryliodonium salt;
- 5 to 10 parts by weight of an anti-adhesion modulator constituted by a silicone polymer an epoxy polydimethylsiloxane which is not polymerized; and

· an anti-stick agent making the composition less tacky prior to polymerization, which comprises at least one vinyl ether compound, and said one vinyl ether compound is present at a concentration of 8 to 12 parts by weight dodecyl monovinyl ether in said stripping composition and 8 to 12 parts by weight of cyclohexane dimethanol divinyl ether in said stripping composition.

17-23. (cancelled)

24. (previously presented) The method according to claim 16, wherein the surface of the mold is coated with a wipe or a cloth impregnated in the stripping composition.

25-26. (cancelled)

- 27. (currently amended) The method according to claim [[26]] $\underline{16}$, wherein the polymerization cycle is 1 hour at 150°C \pm 5°C.
- 28. (currently amended) The method according to claim [[26]] $\underline{16}$, wherein the polymerization cycle is 30 minutes at 100°C.

29. (currently amended) The method according to claim [[21]] 16, wherein the surface of the mold is coated with a wipe or a cloth impregnated in the stripping composition.

30. (cancelled)

31. (previously presented) The method according to claim 16, wherein the composite material part formed in the mold is a helicopter blade or an element of such a blade.

32-33. (cancelled)

- 34. (new) A stripping composition to be applied as a coating on a mold for making a heat curable composite material part, comprising:
- 100 parts by weight of a base ingredient constituted by an epoxy polydimethylsiloxane;
- \cdot 0.5 to 10 parts by weight of a polymerization agent for polymerizing the base ingredient and constituted by a diaryliodonium salt;
- \cdot 5 to 10 parts by weight of an anti-adhesion modulator constituted by an epoxy polydimethylsiloxane which is not polymerized; and
- \cdot an anti-stick agent making the composition less tacky prior to polymerization, which comprises 8 to 12 parts by weight

dodecyl monovinyl ether in the stripping composition and 8 to 12 parts by weight of cyclohexane dimethanol divinyl ether in the stripping composition,

wherein the stripping composition is a solvent-free liquid that is polymerized by heating.